
Numerical optimization of rate coefficients of chemical reactions in C_4F_8 plasma

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Reliable plasma simulation can be carried out with a set of accurate chemical reaction rate coefficients that include every significant chemical reaction occurred in the plasma. Some of the rate coefficients can be collected from the literature of theoretical or experimental researches, but others are hard to achieve. Especially, in the plasma used in the semiconductor industries several hundred reactions should be included in the set, but many of them cannot be achieved from literature with high accuracy. Some of them have large uncertainty and others should be estimated because they are not found in the literature. Then the researchers have been tuned the estimated rate coefficients until the simulation result agree with the experiments. This tuning is just trial and error process, but requires much human effort. In this study numerical optimization software was developed to tune the rate coefficients with much less human effort than previous researches. In the software several numerical optimization algorithms can be used including steepest descent, Newton, modified Newton and Broyden-Fletcher-Goldfarb-Shanno method. A spatially averaged global plasma simulator, K-ODPLASMA, was used to simulate plasma while numerical optimization processes. The numerical optimization software was applied to tune a set of rate coefficients for C_4F_8 plasma which has been used in the etching process of semiconductor industries.

This research was supported by the National Research Council of Science & Technology (NST) grant by the Korea government (MSIP) (No. CAP-17-02-NFRI) and R&D Program through the National Fusion Research Institute (NFRI) funded by the Korea government.